25 Graduate Student Award Finalists Participate in Special Session at MRS Fall Meeting

Twenty-five graduate student award finalists are participating in a special student talk session during the 1989 MRS Fall Meeting in Boston. A recent addition to the criteria for selecting award recipients, this special session is being implemented at the Fall Meeting to reflect the growing competitiveness of the graduate student awards program, to improve the selection process, and to give more visibility to the graduate students at the meeting.

The finalists are presenting 10-minute talks on their work Tuesday, November 28 from 12:10 to 1:30 p.m. in five designated rooms at the Boston Marriott Hotel. Among the judges will be organizers from the symposia in which the finalists are participating, members of the MRS Awards Committee, and other MRS representatives. MRS Fall Meeting participants are also invited to attend.

Graduate student awards will be presented at the Von Hippel Award Ceremony, Wednesday, November 29 at 6 p.m. in the Boston Marriott Hotel. Following is a list of the finalists, the titles of their papers, and the symposia in which the complete papers are being presented.

Graduate Student Award Finalists

1989 MRS Fall Meeting

Terry Lynn Alford, Cornell University, "Ion-Beam Synthesis of Buried Yttrium Silicide," (Symposium A)

John F. Ankner, University of Illinois, "Neutron Reflectivity Study of GD-Y Interface," (Symposium J)

Louis Breaux, University of Texas, "Remote Plasma-Enhanced CVD of Epitaxial Silicon on Silicon (100) at 150°C," (Symposium I)

David Ward Brown, University of California-Davis, "Formation of Buried Elemental Layers Using Ion Implantation," (Symposium A)

Ju Ren Ding, Tsinghua University, Beijing, "Ion Beam Method to Study Fractal Aggregation of Magnetic Particles in Thin Films," (Symposium A)

Vinayak P. Dravid, Lehigh University, "Plan-View CBED Studies of NiO-ZrO_2(CaO) Interfaces," (Symposium C)

Hailing Duan, John Hopkins University, "Studies on the Formation of Switching and Memory Storage Materials Constructed from Metallo-Organic Charge-Transfer Salts," (Symposium Q)

Hilary L. Hampsch, Northwestern University, "Second Order Nonlinear Optics and Polymer Physics of Corona Poled Polymer Films," (Symposium Q)

Arun Inam, Rutgers University, "Josephson Weak-Links Fabricated from Heteroepitaxial $YBa_2Cu_3O_{7-x}$/$PrBa_2Cu_3O_{7-x}$/$YBa_2Cu_3O_{7-x}$ Multilayers," (Symposium M)

Forrest Kaatz, University of Pennsylvania, "Epitaxial Growth of $TbSi_2$ on Si(111)," (Symposium D)

Robert R. Keller, University of Minnesota, "Electron Channeling Analysis of Elastic Strains in InGaAs Thin Films," (Symposium D)

Qiyuan Ma, Columbia University, "Use of Si-YBaCuO Intermixed System for Patterning of Superconducting Thin Films," (Symposium M)

John F. Marko, Massachusetts Institute of Technology, "Weighted-Density Theory of Phase Transitions in Fluids Composed of Anisotropic Particles," (Symposium V)

Anne W. Mayes, Northwestern University, "Microphase Separation in Multiblock Copolymer Melts," (Symposium S)

Rejean Munger, University of Waterloo, Ontario, "Partial Superconductivity in YBa_2Cu3O_7 at $90 < T < 300$ K," (Symposium M)

Linda S. Sapochak, University of Southern California, "Effects of Conjugation Length and Substituents on the Conductivity of Oxidatively Doped a,w-Diphenylpolenes," (Symposium Q)

Linda S. Schadler, University of Pennsylvania, "Interphase Behavior of Cyclic Fatigue of Monofilament Composites," (Symposium N)

Xiangdong Shi, University of Pennsylvania, "Sound Velocity Studies of the Bechgaard Salts $(TMTSF)_2ClO_4$ and $(TMTSF)_2PF_6$," (Symposium Q)

Rajiv K. Singh, North Carolina State University, "Pulsed Laser Technique for Deposition of Superconducting Thin Films: Deposition Physics and *In-Situ* Processing," (Symposium M)

Leland Scott Swanson, Iowa State University, "Photoluminescence, ESR, and ODMR Studies of Pristine and Photodegraded Poly(3-Hexylthiopohene) Films and Solutions," (Symposium Q)

Igor Szafranek, University of Illinois at Urbana-Champaign, "Reassessment of Acceptor Passivation Mechanism in p-Type Hydrogenated GaAs," (Symposium G)

Lisa Tietz, Cornell University, "The Structure of Interfaces in Oxide Heterojunctions Formed by CVD," (Symposium C)

Karen I. Winey, University of Massachusetts, "The Ordered Bicontinuous Double Diamond Structure in Blends of Diblock Copolymer and Homopolymer," (Symposium O)

Dan Q. Wu, State University of New York at Stony Brook, "Small-Angle X-Ray Scattering on Poly(Ethylene-Methacrylic Acid) Lead and Lead Sulfide Ionomers," (Symposium O)

Satoshi Yamauchi, Tohoku University, Japan, "Plasma-Assisted Epitaxial Growth of ZnSe Films in Hydrogen Plasma," (Symposium E) MRS

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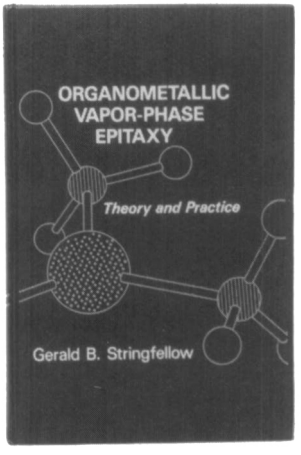

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Hours

Tuesday, November 28 . . . . . 12:00 p.m.-7:00 p.m.
(Reception 5:00 p.m.-7:00 p.m.)
Wednesday, November 29 . . . . . 9:00 a.m.-5:00 p.m.
Thursday, November 30 . . . . . 9:00 a.m.-2:00 p.m.

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Doug Lowndes, Oak Ridge National Laboratory, (615) 574-6306

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■ SYMPOSIUM S / SYNTHESIS AND PROPERTIES OF NEW CATALYSTS: UTILIZATION OF NOVEL MATERIALS COMPONENTS AND SYNTHETIC TECHNIQUES

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Edward W. Corcoran, Exxon Research and Engineering, (201) 730-2465
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■ SYMPOSIUM U / ADVANCED TOMOGRAPHIC IMAGING METHODS FOR THE STUDY OF MATERIALS

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■ SYMPOSIUM V / BIOMATERIALS

(Chairs to be announced)

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